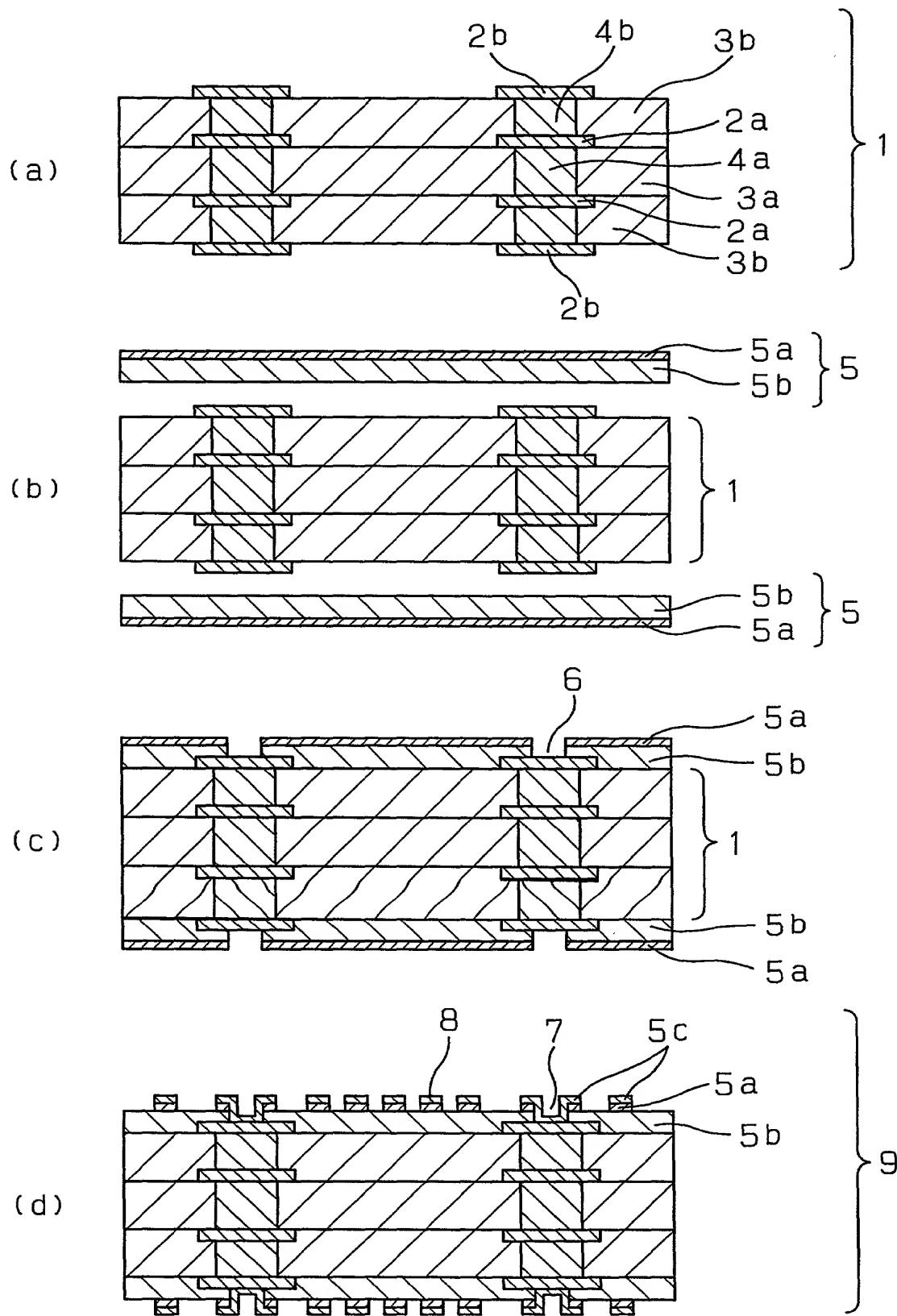
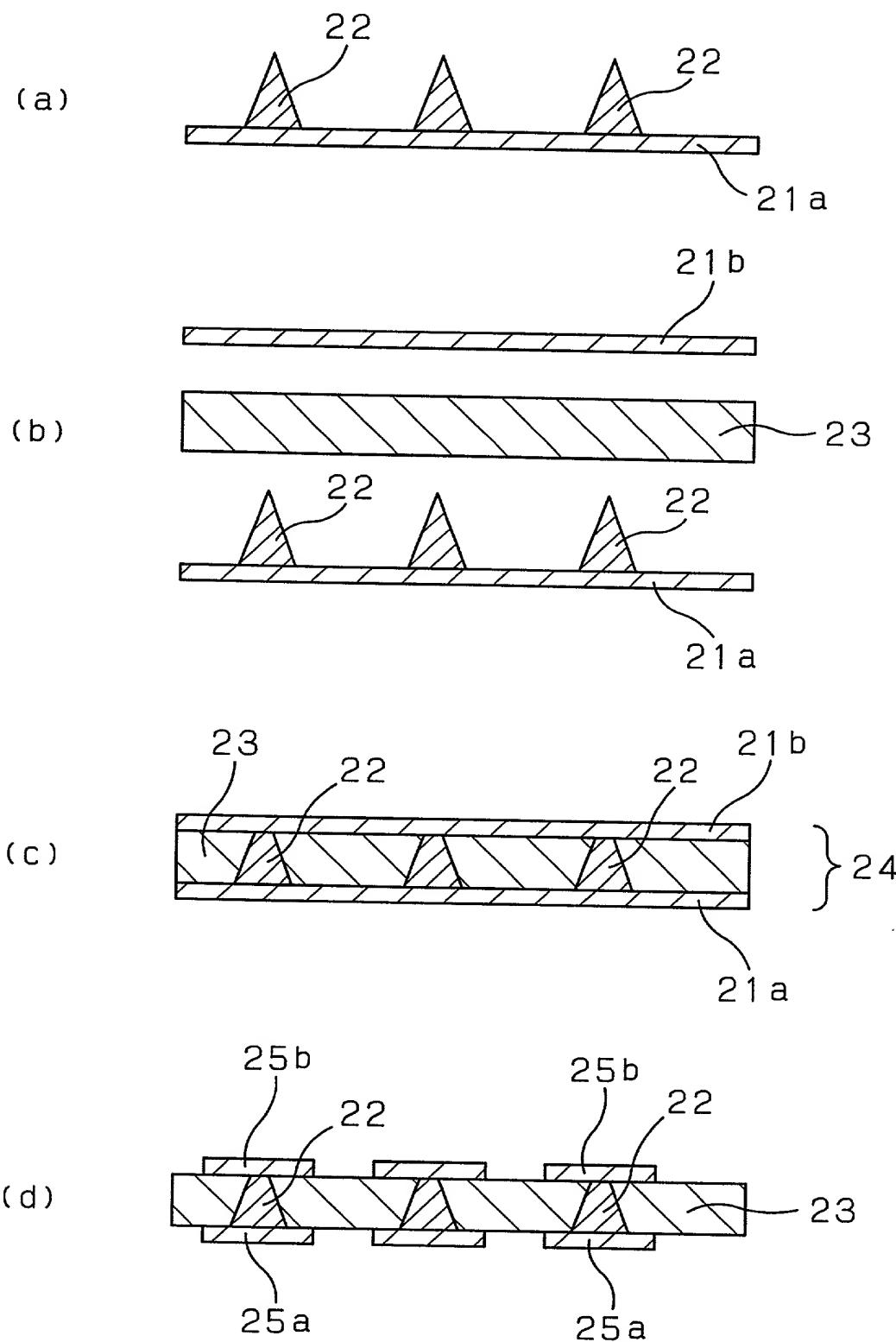


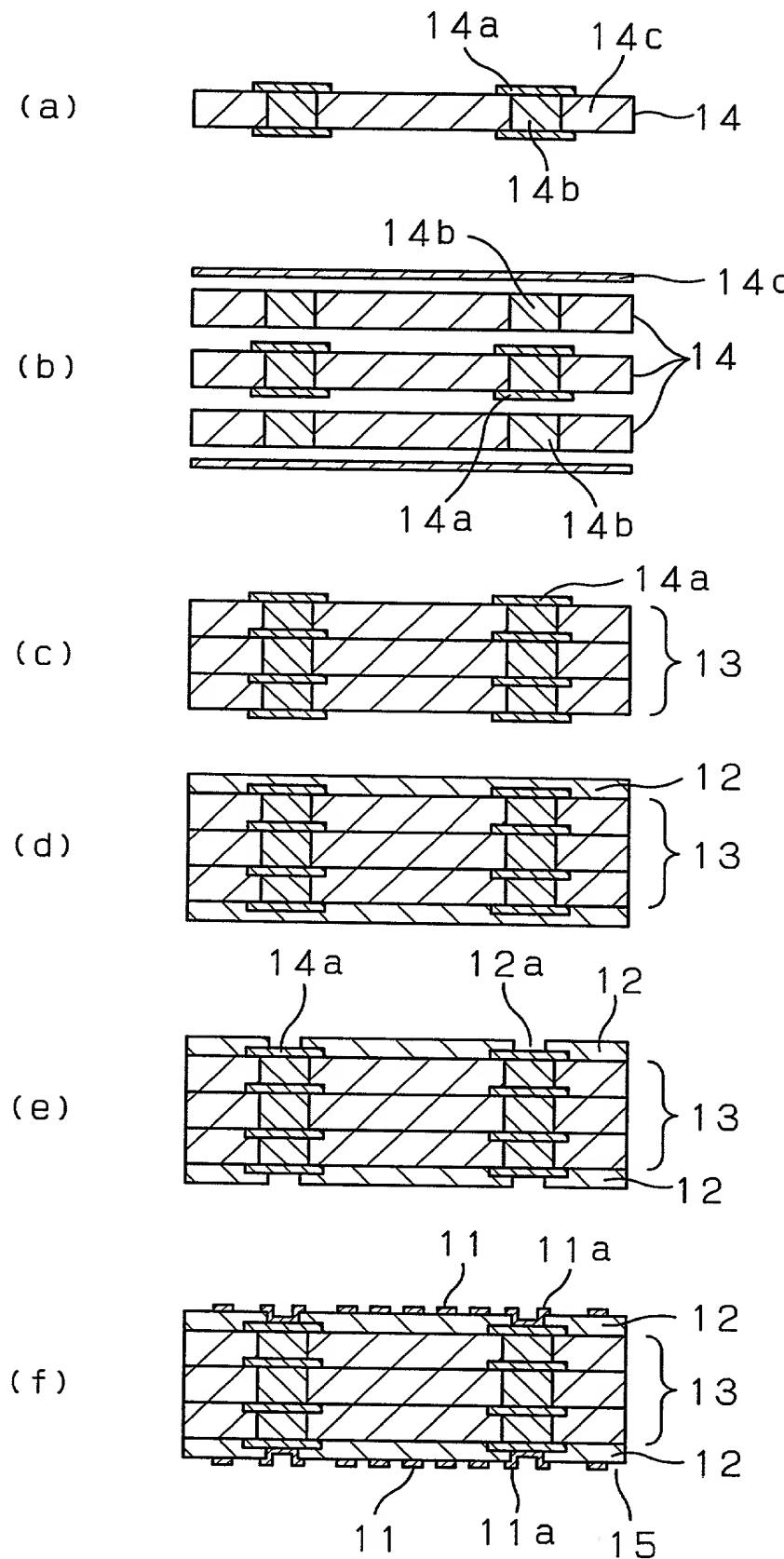
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Fig. 1

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Fig. 2



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Fig. 3



Key to Reference Alphanumeric Characters

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|----|---|
| 1 | Inner Layer Material |
| 2 | Inner Conductive Pattern |
| 2a | First Inner Conductive Pattern |
| 10 | 2b Second Inner Conductive Pattern |
| 3 | Insulating Substrate for Inner Layer Material |
| 3a | First Insulating Substrate |
| 3b | Second Insulating Substrate |
| 4 | Conductive Paste and Interstitial Via Hole |
| 15 | 4a First Conductive Paste, Interstitial Via Hole |
| | 4b Second Conductive Paste, Interstitial Via Hole |
| | 5 Metal Foil with Insulating Resin |
| | 5a Metal Foil |
| | 5b Insulating Resin |
| 20 | 5c Metal Plating Layer |
| | 6 Non-through Hole |
| | 7 Surface Via Hole (SVH) with Metal Plating Applied to Non-through Hole |
| | 8 Outer Conductive Pattern |
| 25 | 9 Multilayer Printed Wiring Board |
| | 21a First Copper Foil |
| | 21b Second Copper Foil |
| | 22 Conductor Projection |
| | 23 Aramid Nonwoven Fabric Base Material Epoxy Resin Prepreg |
| 30 | 24 Laminated Board for Inner Layer |

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- 25 Inner Conductor Circuit
- 25a First Inner Conductor Circuit, First Inner Conductive Pattern
- 25b Second Inner Conductor Circuit, Second Inner Conductive Pattern